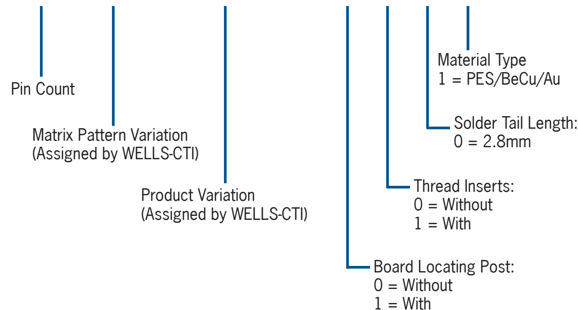
3M™ Textool™ BGA/LGA LOW CLOSING FORCE LIDDED SOCKETS, 1.27mm TYPE III

Low Profile Version

Solution provided by: 3M

- Modular construction allows for cost effective socket proliferation for standard and custom packages
- Coarse alignment on device body followed by a secondary fine alignment to the solder balls
- Flat contact head that provides for minimum solder ball deformation
- Can be adapted to either BGA or LGA formats
- Built-in alignment plates
- Available with screw inserts as standard option
- Lid closing force reduction ration of 50 to 1
- Accepts maximum pin count of 700 and maximum device thickness of 4.00mm
- Thru hole design

DESCRIPTION & ORDERING INFORMATION



Device Pitch (mm)	Device Length (mm)	Device Width (mm)	Device Matrix	Alignment Method	Type Accepted
1.27	37.50	37.50	27 X 27	BALL	BALL
	37.50	37.50	29 X 29	BALL	BALL
	40.00	40.00	29 X 29	BALL	BALL
	40.00	40.00	30 X 30	BALL	BALL
	40.00	40.00	31 X 31	BALL	BALL
	41.00	41.00	31 X 31	BALL	BALL
	42.00	42.00	32 X 32	BODY	BALL or PAD (LGA)
	42.50	42.50	31 X 31	BALL	BALL
	42.50	42.50	32 X 32	BALL	BALL
	42.50	42.50	33 X 33	BALL	BALL
	43.00	43.00	33 X 33	BALL	BALL
	45.00	45.00	33 X 33	BALL	BALL
	45.00	45.00	34 X 34	BALL	BALL
	45.00	45.00	35 X 35	BALL	BALL
	47.50	47.50	35 X 35	BALL	BALL
	47.50	47.50	36 X 36	BALL	BALL
	47.50	47.50	37 X 37	BALL	BALL
	50.00	50.00	39 X 39	BALL	BALL

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